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(12) **United States Design Patent**
Cola et al.

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(54) **FLEXIBLE HEAT SINK**

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(73) Assignee: **CARBICE CORPORATION**, Atlanta, GA (US)

(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **15 Years**

(21) Appl. No.: **29/703,508**

(22) Filed: **Aug. 28, 2019**

(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**

(58) **Field of Classification Search**
USPC D13/179
CPC . H05K 7/20254; H05K 7/20418; F28F 3/022; F28F 3/04; F28F 21/065; H01L 23/367; H01L 23/3672; H01L 23/3677; H01L 23/36; G02B 1/111; A61B 17/50; A61M 37/0015
See application file for complete search history.

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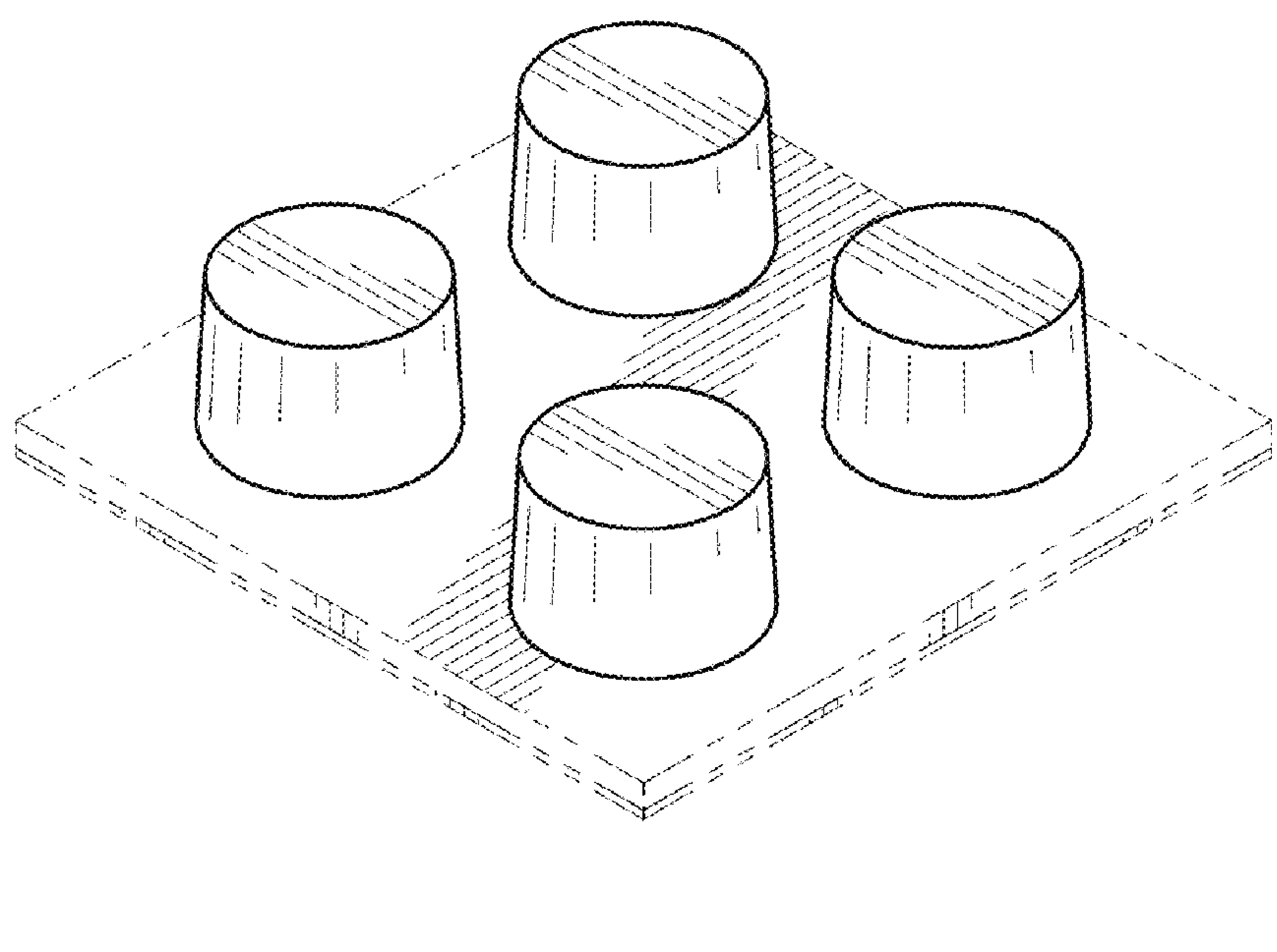
(57) **CLAIM**

We claim the ornamental design for a flexible heat sink, as shown and described.

DESCRIPTION

FIG. **1** is a top isometric view of a flexible heat sink showing our new design;
FIG. **2** is a front elevation view thereof, each of the right elevation, left elevation, and rear elevation views being a mirror image thereof;
FIG. **3** is a top view thereof;
FIG. **4** is a bottom view thereof;
FIG. **5** is a top isometric view of the flexible heat sink illustrated in FIGS. **1** to **4** on a curved surface;
FIG. **6** is a front elevation view thereof, the rear elevation view being a mirror image thereof;
FIG. **7** is a top view thereof; and,
FIG. **8** is a bottom view thereof.
The shade lines in the Figures show contour and not surface ornamentation.
The broken dash-dot-dot lines in the views define boundary lines are not part of the claimed design. The evenly broken lines are used to depict environmental features for illustrative purposes only and form no part of the claimed design.

1 Claim, 2 Drawing Sheets



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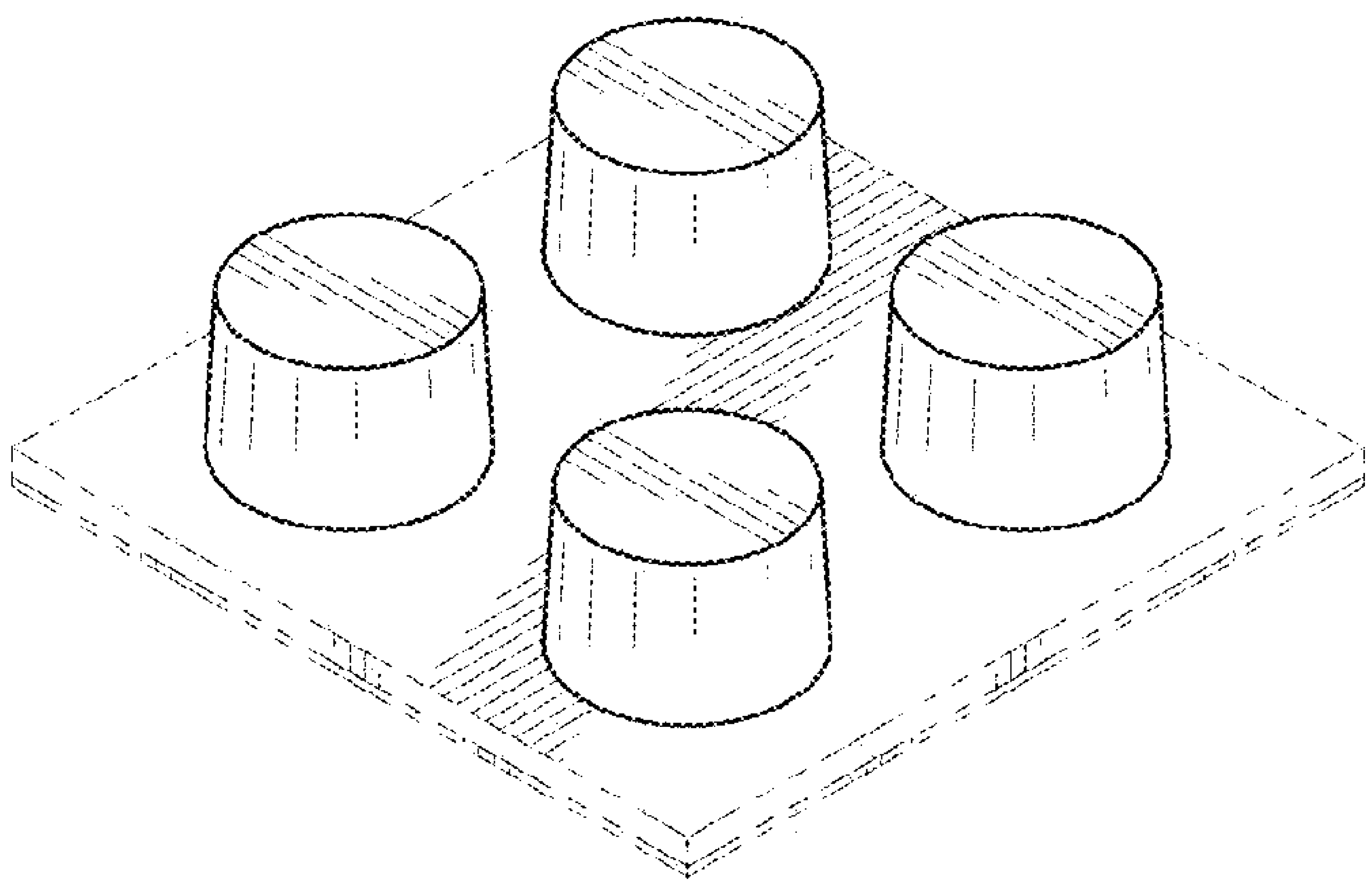


FIG. 1

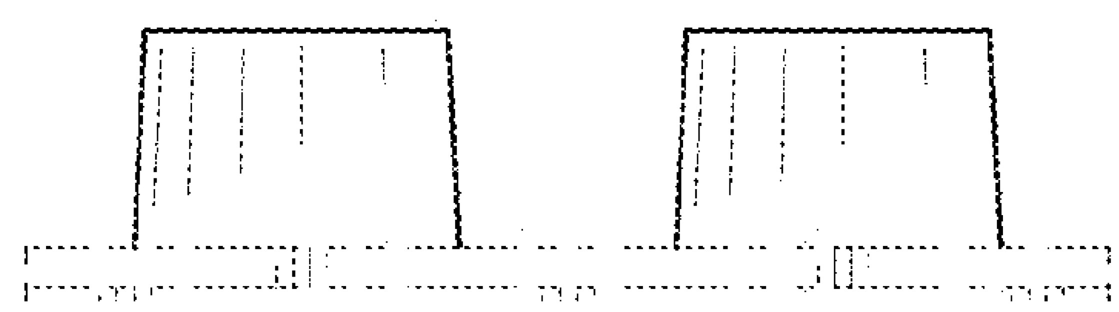


FIG. 2

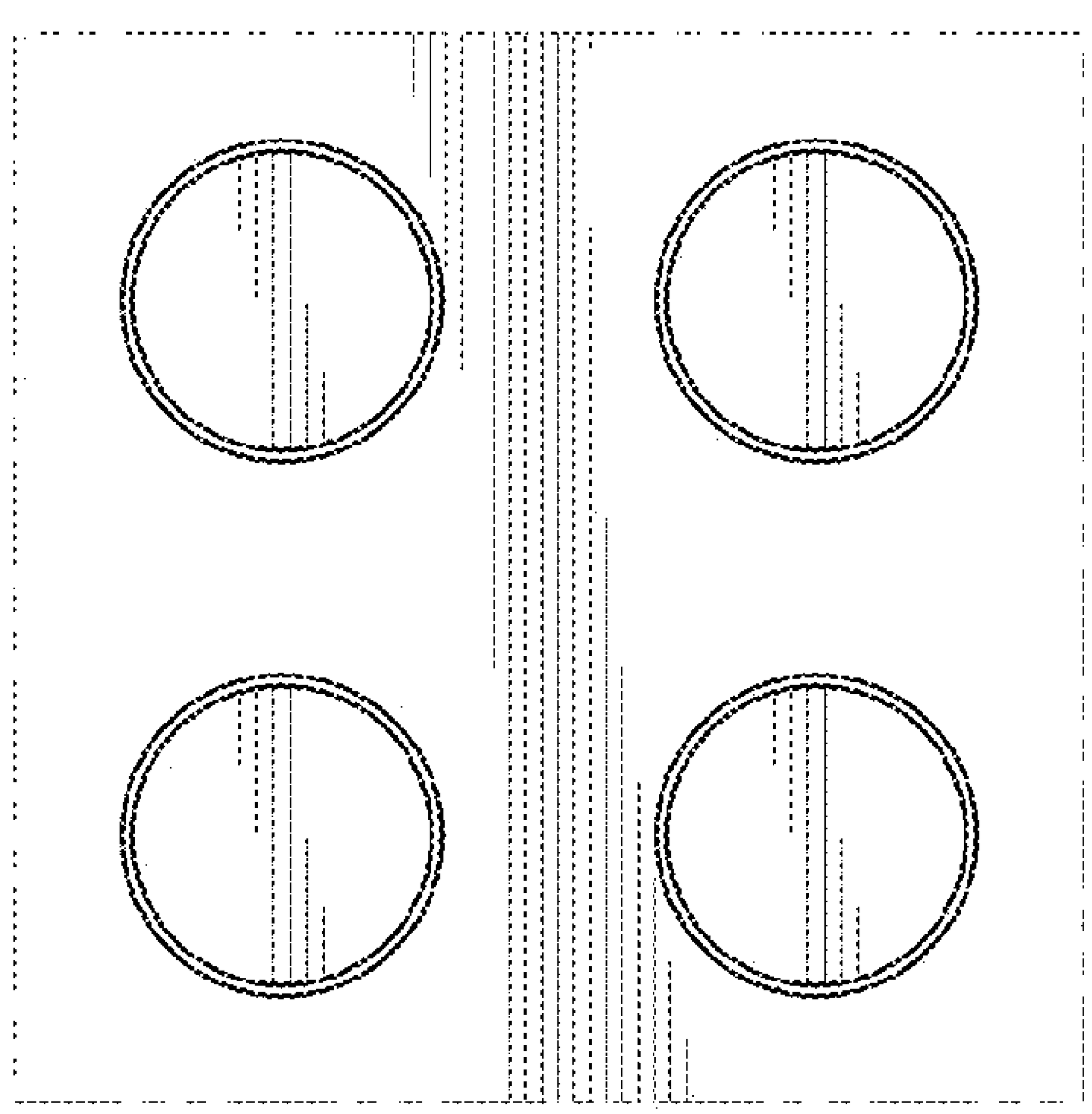


FIG. 3

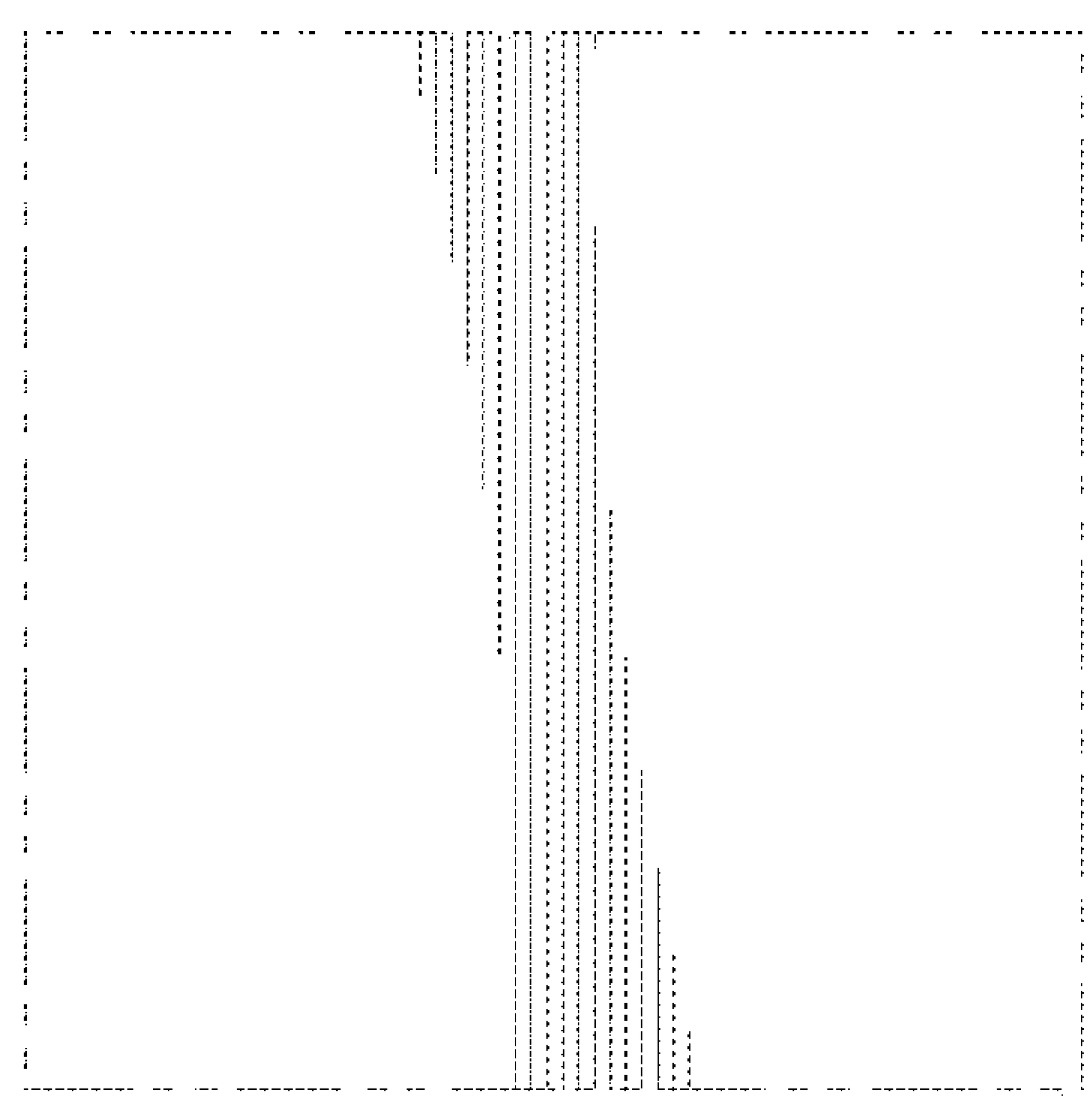


FIG. 4

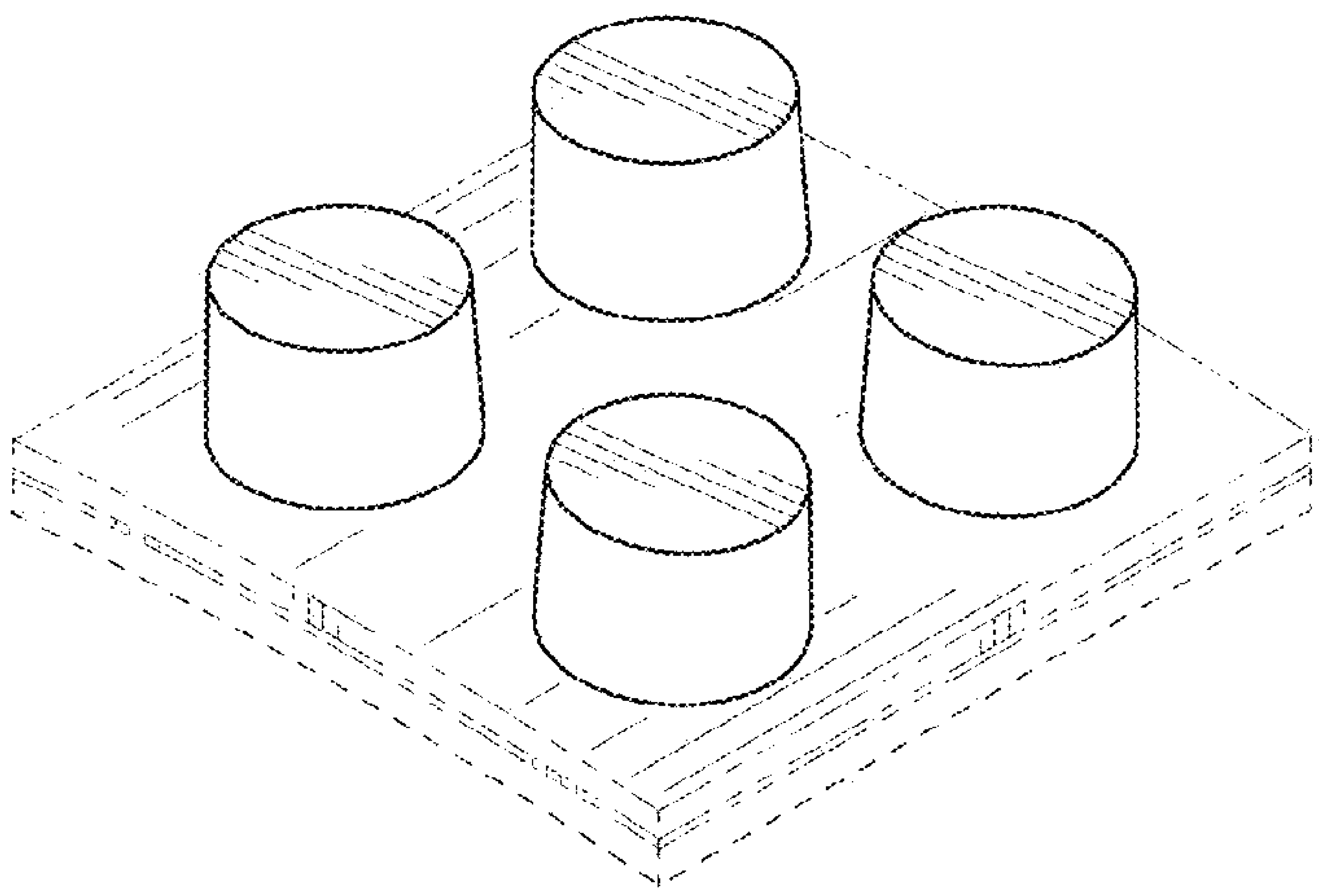
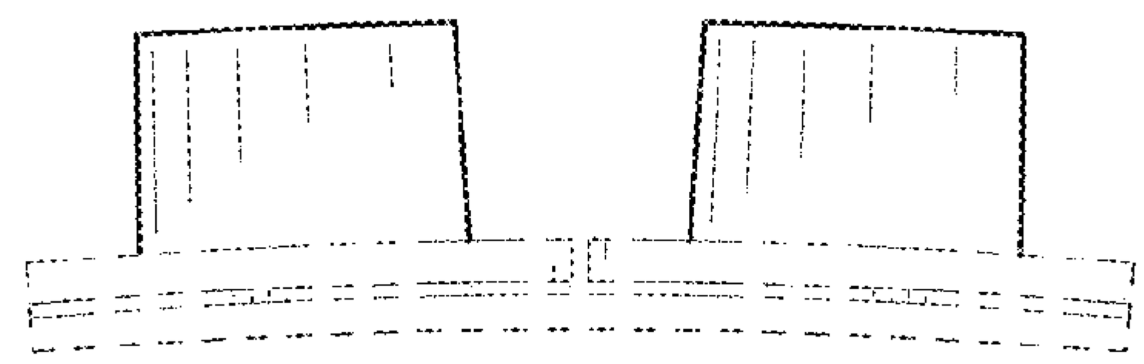


FIG. 5



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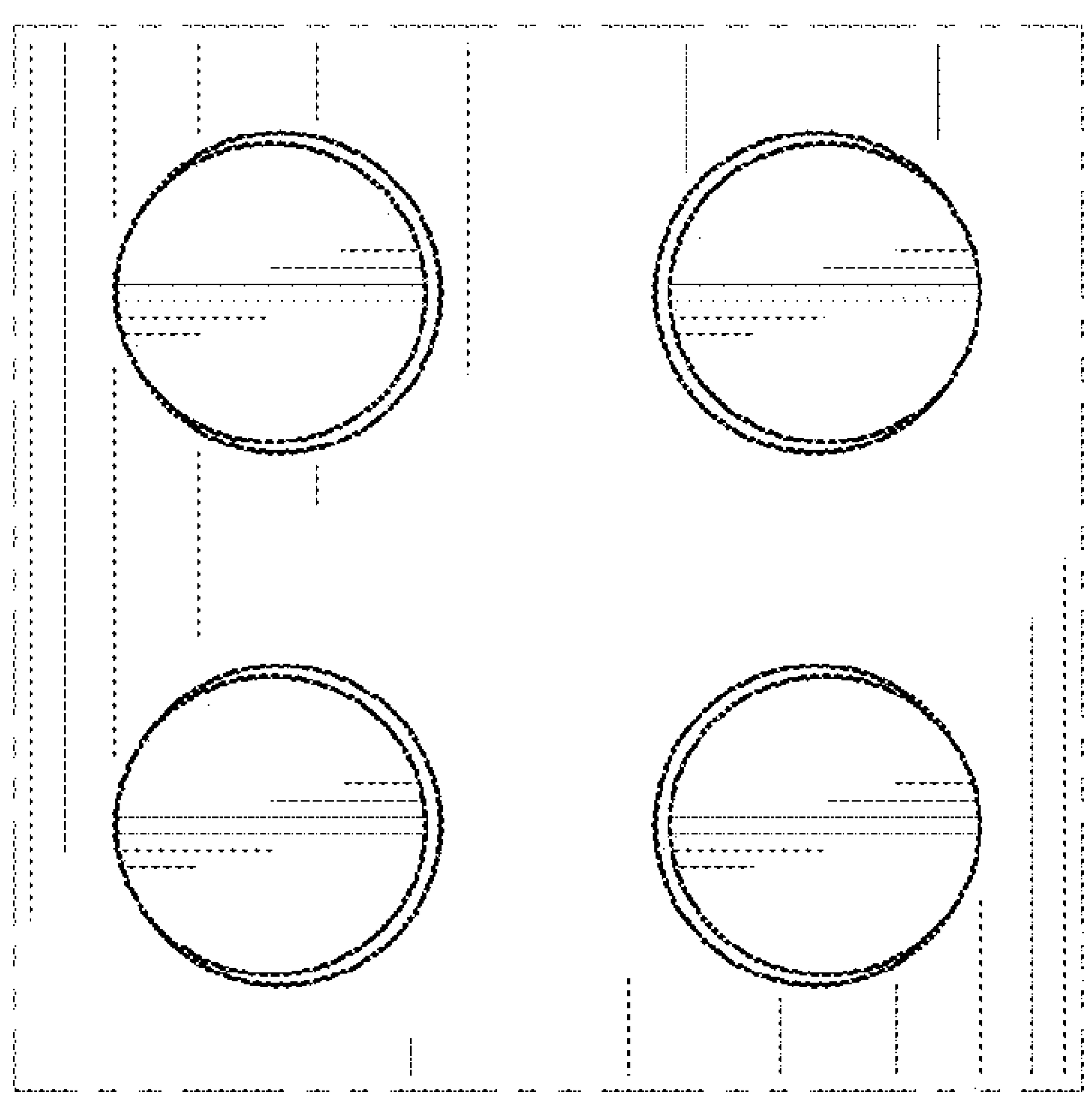

FIG. 7

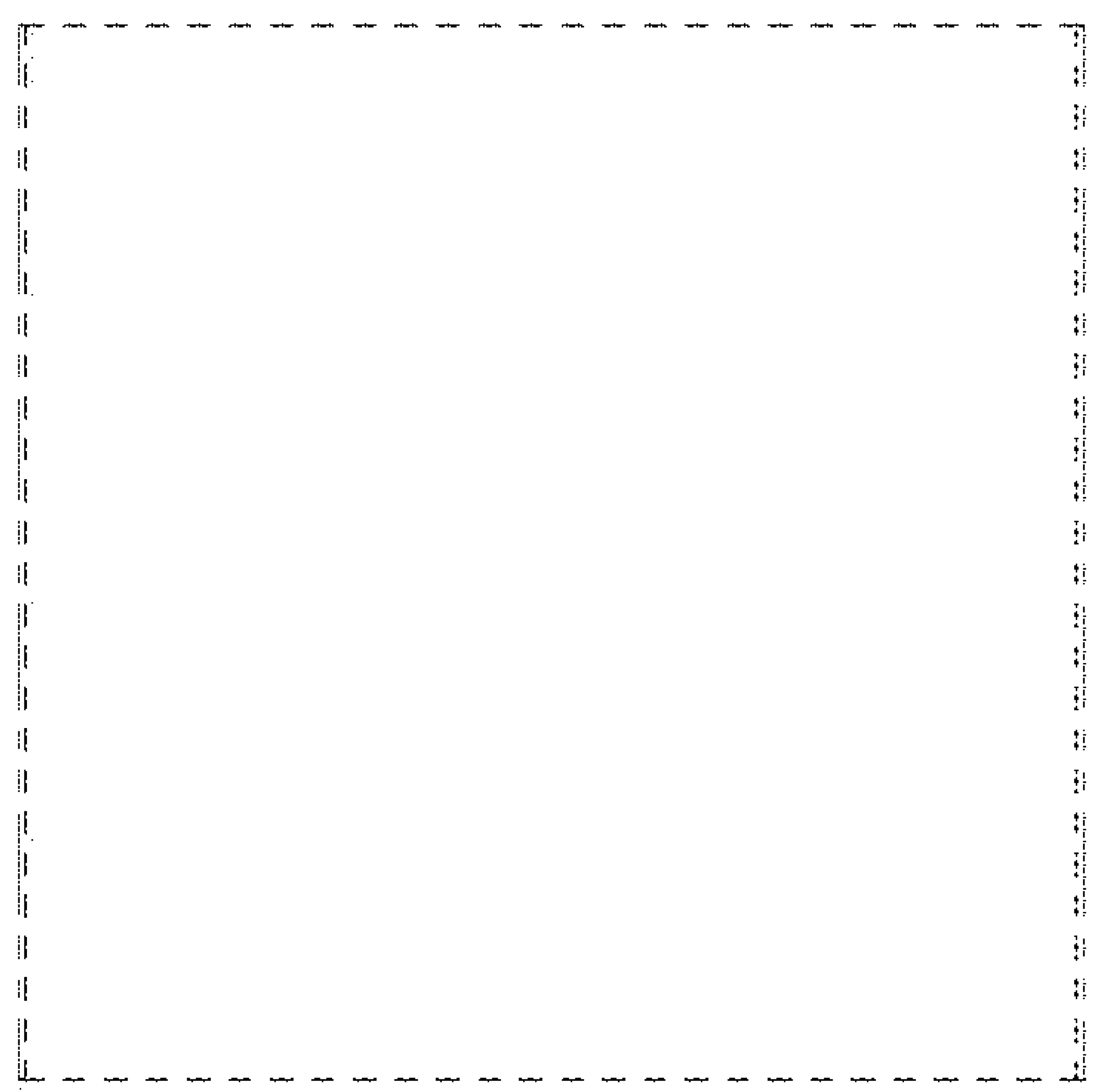

FIG. 8